 Bidirectional Bus Transceivers in	DW OR N PACKAGE
High-Density 20-Pin Packages	(TOP VIEW)
 Lower-Power Versions of SN74ALS640B	DIR $\begin{bmatrix} 1 & 20 \end{bmatrix}$ V _{CC}
and SN74ALS645A	A1 $\begin{bmatrix} 2 & 19 \end{bmatrix}$ OE
 Package Options Include Plastic	A2 [] 3 18] B1
Small-Outline (DW) Packages and Standard	A3 [] 4 17] B2
Plastic (N) 300-mil DIPs	A4 [] 5 16] B3
description	A5 [] 6 15]] B4 A6 [] 7 14 [] B5
These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus,	A7 [8 13] B6 A8 [9 12] B7 GND [10 11] B8

(DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated. The SN74ALS1640A features inverting logic, while the SN74ALS1645A features noninverting logic.

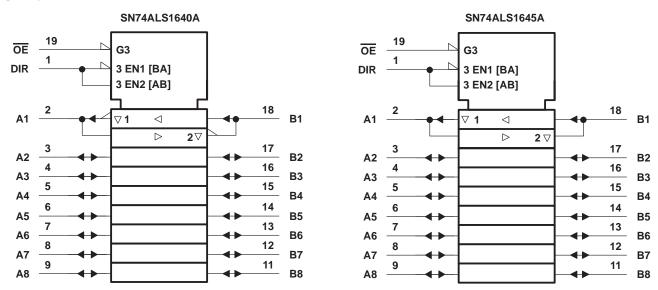
The SN74ALS1640A and SN74ALS1645A are characterized for operation from 0°C to 70°C.

depending on the level at the direction-control

	FUNCTION TABLE							
INP	UTS	OPERATION						
OE	DIR	SN74ALS1640A	SN74ALS1645A					
L	L	B data to A bus	B data to A bus					
L	Н	A data to B bus	A data to B bus					
н	Х	Isolation	Isolation					

logic symbols[†]

d



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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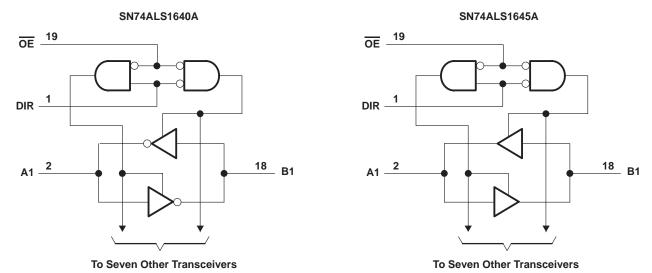


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SN74ALS1640A, SN74ALS1645A OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SDAS246B – DECEMBER 1982 – REVISED FEBRUARY 1997

SDAS246B - DECEMBER 1982 - REVISED FEBRUARY 19

logic diagrams (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I : All inputs	7 V
I/O ports	5.5 V
Package thermal impedance, θ_{JA} (see Note 1): DW package	97°C/W
N package	67°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		-	4ALS164 4ALS164	-	UNIT
		MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
ЮН	High-level output current			-15	mA
IOL	Low-level output current			16	mA
ТА	Operating free-air temperature	0		70	°C



SN74ALS1640A, SN74ALS1645A **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS SDAS246B - DECEMBER 1982 - REVISED FEBRUARY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TES	TEST CONDITIONS				
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.5	V
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			
Vон		V _{CC} = 4.5 V	I _{OH} = –3 mA	2.4	3.2		V
		$v_{CC} = 4.5 v$	I _{OH} = -15 mA	2			
N			IOL = 8 mA		0.25	0.4	V
VOL		$V_{CC} = 4.5 V$	I _{OL} = 16 mA		0.35	0.5	v
1.	Control inputs		V _I = 7 V			0.1	mA
tı –	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1	mA
1	Control inputs		V ₁ = 2.7 V			20	
ΊН	A or B ports‡	V _{CC} = 5.5 V,	v = 2.7 v			20	μA
	Control inputs					-0.1	mA
IIL A or B ports‡		V _{CC} = 5.5 V,	$V_{ } = 0.4 V$			-0.1	mA
۱ ₀ §		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
	SN74ALS1640A	V _{CC} = 5.5 V			18	32	mA
Icc	SN74ALS1645A	V _{CC} = 5.5 V			25	38	шА

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

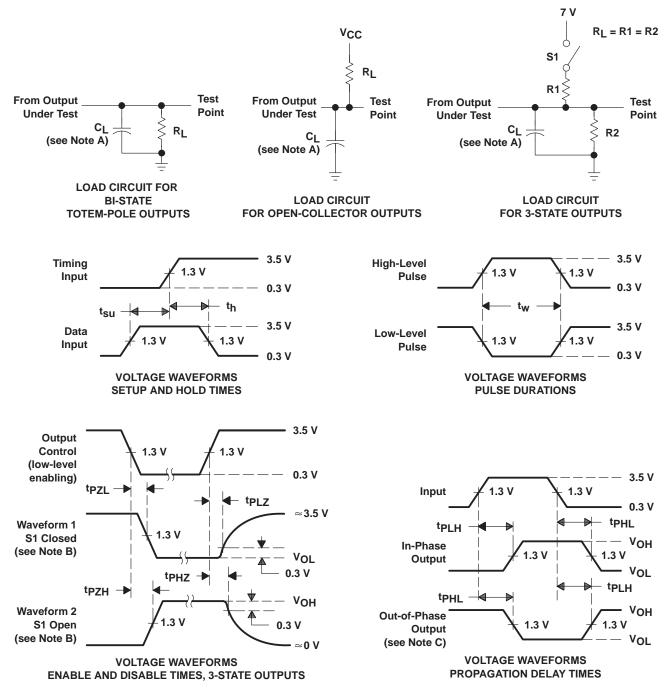
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C R R	L = 50 p 1 = 500 2 = 500	Ω,	7 3	UNIT
			SN74ALS	61640A	SN74ALS		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	DenA	4	15	2	13	ns
^t PHL	AUD	B or A	2	10	2	13	115
^t PZH	OE	A an D	5	20	8	25	ns
tPZL	ÛE	A or B	5	22	8	25	115
^t PHZ	OE	A or D	2	10	2	12	ns
t _{PLZ}	UE	A or B	5	13	3	18	115

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

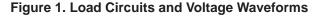






NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS1640AN	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI	Samples Not Available
SN74ALS1645AN	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
SN74ALS1645ANE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
SN74ALS1645ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74ALS1645ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74ALS1645ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal					
Device	Package		Reel	Reel Width	A0 (mp

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS1645ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS1645ANSR	SO	NS	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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